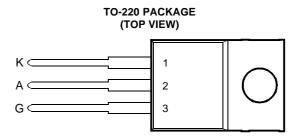
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- 5 A Continuous On-State Current
- 30 A Surge-Current
- Glass Passivated Wafer
- 400 V to 800 V Off-State Voltage
- Max I_{GT} of 200 μA



Pin 2 is in electrical contact with the mounting base.

MDC1ACA

absolute maximum ratings over operating case temperature (unless otherwise noted)

RATING	SYMBOL	VALUE	UNIT	
	TIC106D		400	
Repetitive peak off-state voltage (see Note 1)	TIC106M	V	600	V
	TIC106S	V _{DRM}	700	v
	TIC106N		800	
	TIC106D		400	
Depetitive peak reverse veltere	TIC106M	N/	600	V
Repetitive peak reverse voltage	TIC106S	V _{RRM}	700	v
	TIC106N		800	
Continuous on-state current at (or below) 80°C case temperature (see Note 2)	I _{T(RMS)}	5	A	
Average on-state current (180° conduction angle) at (or below) 80°C case temperature			3.2	А
(see Note 3)	I _{T(AV)}	3.2	A	
Surge on-state current (see Note 4)			30	А
Peak positive gate current (pulse width \leq 300 µs)			0.2	А
Peak gate power dissipation (pulse width \leq 300 µs)			1.3	W
Average gate power dissipation (see Note 5)			0.3	W
Operating case temperature range			-40 to +110	°C
Storage temperature range			-40 to +125	°C
Lead temperature 1.6 mm from case for 10 seconds			230	°C

NOTES: 1. These values apply when the gate-cathode resistance R_{GK} = 1 k\Omega.

3. This value may be applied continuously under single phase 50 Hz half-sine-wave operation with resistive load. Above 80°C derate linearly to zero at 110°C.

4. This value applies for one 50 Hz half-sine-wave when the device is operating at (or below) the rated value of peak reverse voltage and on-state current. Surge may be repeated after the device has returned to original thermal equilibrium.

5. This value applies for a maximum averaging time of 20 ms.



^{2.} These values apply for continuous dc operation with resistive load. Above 80°C derate linearly to zero at 110°C.

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electrical characteristics at 25°C case temperature (unless otherwise noted)

PARAMETER			TEST CONDITIONS			TYP	MAX	UNIT
I _{DRM}	Repetitive peak off-state current	V _D = rated V _{DRM}	R _{GK} = 1 kΩ	T _C = 110°C			400	μA
I _{RRM}	Repetitive peak reverse current	V_R = rated V_{RRM}	$I_{G} = 0$	$T_{\rm C} = 110^{\circ}{\rm C}$			1	mA
I _{GT}	Gate trigger current	V _{AA} = 6 V	R _L = 100 Ω	$t_{p(g)} \ge 20 \ \mu s$		60	200	μΑ
V _{GT}	Gate trigger voltage	V _{AA} = 6 V t _{p(g)} ≥ 20 µs	R _L = 100 Ω R _{GK} = 1 kΩ	T _C = - 40°C			1.2	
		$V_{AA} = 6 V$ $t_{p(g)} \ge 20 \ \mu s$	R _L = 100 Ω R _{GK} = 1 kΩ		0.4	0.6	1	V
		V _{AA} = 6 V t _{p(g)} ≥ 20 µs	R _L = 100 Ω R _{GK} = 1 kΩ	T _C = 110°C	0.2			
Ι _Η	Holding current	$V_{AA} = 6 V$ Initiating I _T = 10 mA	R_{GK} = 1 k Ω	T _C = - 40°C			8	mA
		$V_{AA} = 6 V$ Initiating I _T = 10 mA	R_{GK} = 1 k Ω				5	110 (
V_{TM}	Peak on-state voltage	I _{TM} = 5 A	(See Note 6)				1.7	V
dv/dt	Critical rate of rise of off-state voltage	V_D = rated V_D	$R_{GK} = 1 \ k\Omega$	T _C = 110°C		10		V/µs

NOTE 6: This parameter must be measured using pulse techniques, $t_p = 300 \ \mu$ s, duty cycle $\le 2 \ \%$. Voltage sensing-contacts, separate from the current carrying contacts, are located within 3.2 mm from the device body.

thermal characteristics

PARAMETER			TYP	MAX	UNIT
R_{\thetaJC}	Junction to case thermal resistance			3.5	°C/W
R _{θJA}	Junction to free air thermal resistance			62.5	°C/W

resistive-load-switching characteristics at 25°C case temperature

	PARAMETER	TEST CONDITIONS			MIN	ТҮР	MAX	UNIT
t _{gt}	Gate-controlled turn-on time	I _T = 5 A	I _G = 10 mA	See Figure 1		1.75		μs
t _q	Circuit-commutated turn-off time	I _T = 5 A I _{RM} = 8 A	I _G = 10 mA	See Figure 2		7.7		μs

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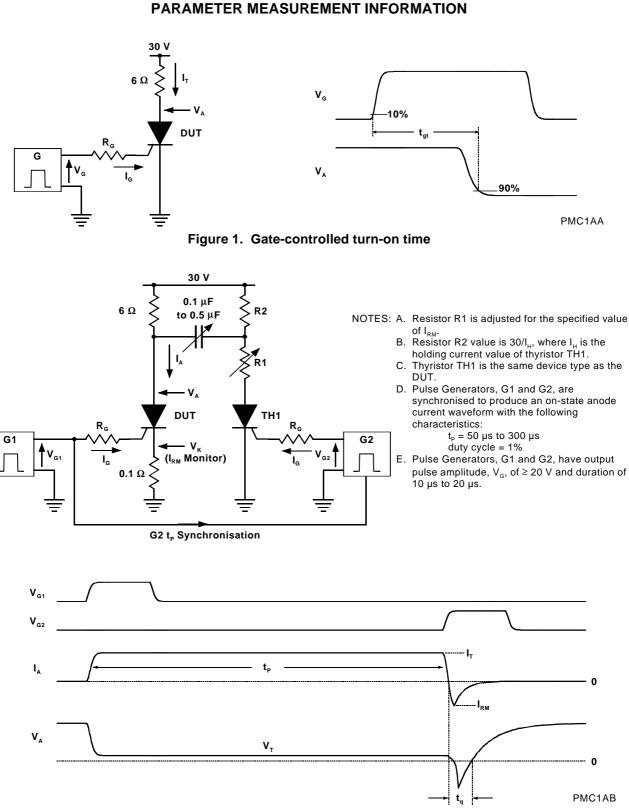
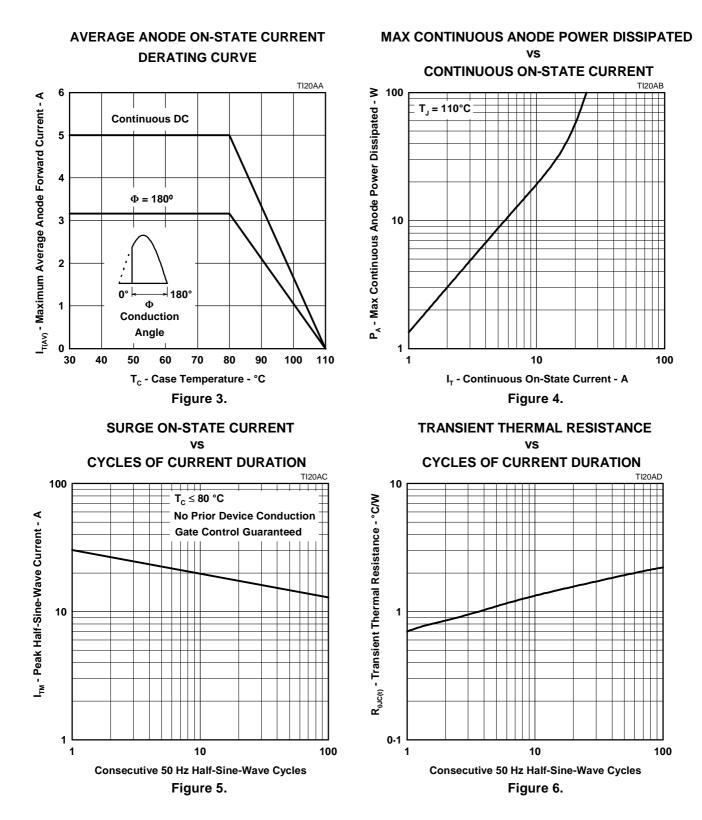


Figure 2. Circuit-commutated turn-off time

PRODUCT INFORMATION

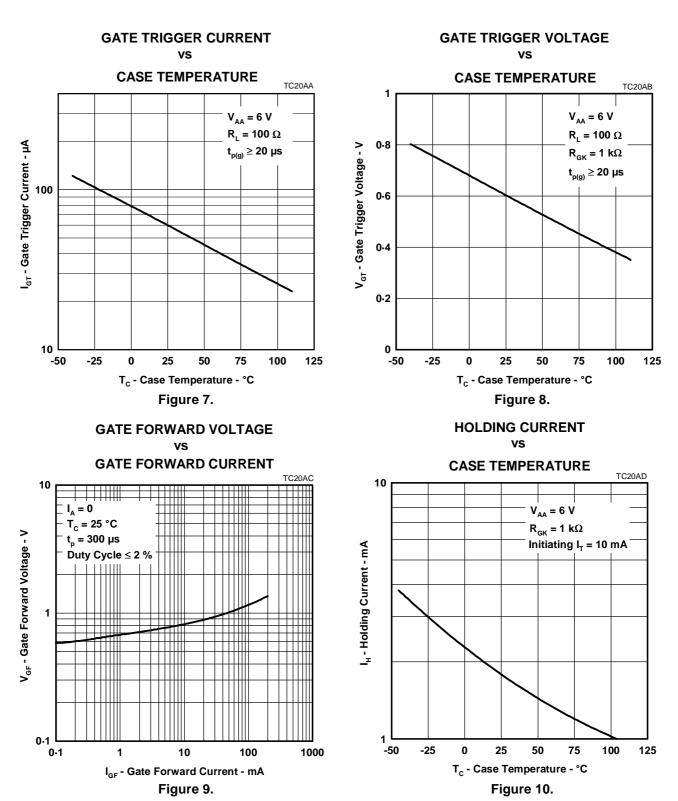
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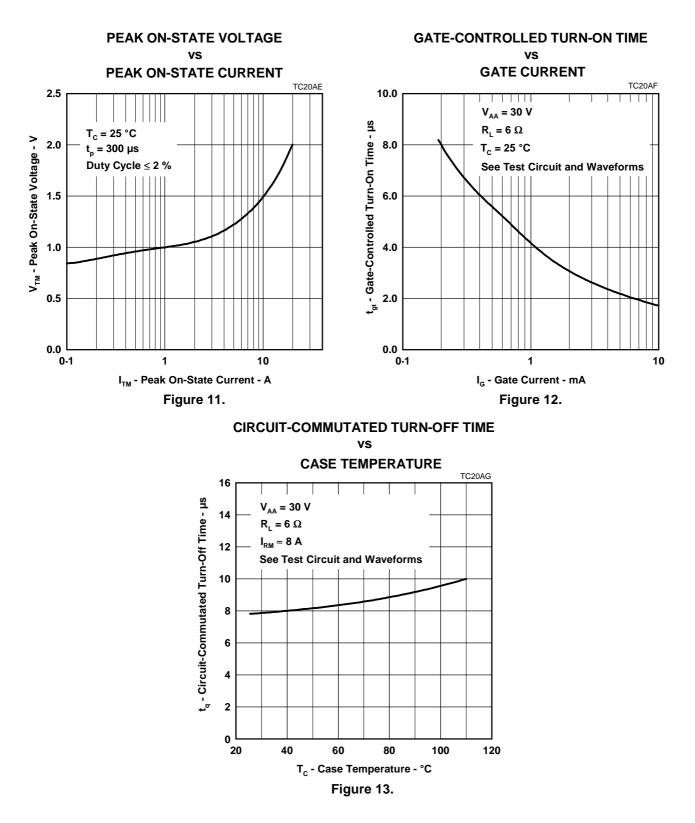


TYPICAL CHARACTERISTICS



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TYPICAL CHARACTERISTICS



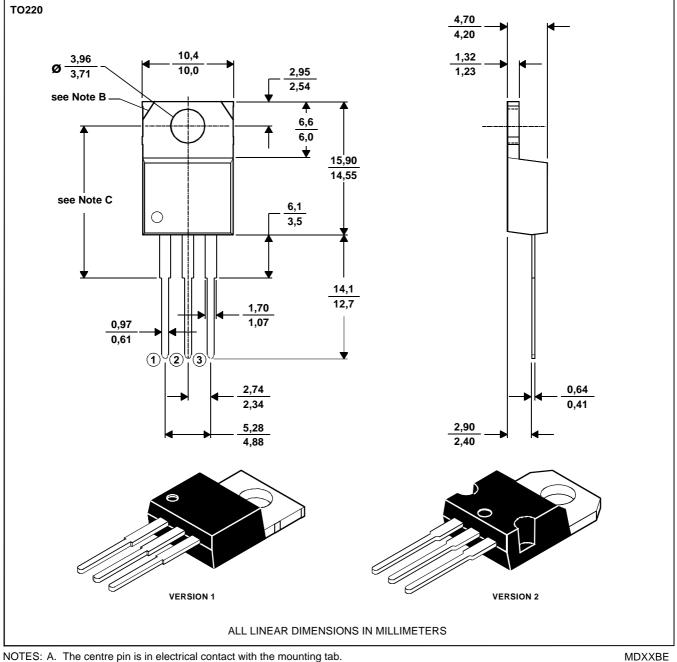
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MECHANICAL DATA

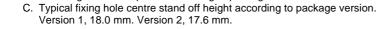
TO-220

3-pin plastic flange-mount package

This single-in-line package consists of a circuit mounted on a lead frame and encapsulated within a plastic compound. The compound will withstand soldering temperature with no deformation, and circuit performance characteristics will remain stable when operated in high humidity conditions. Leads require no additional cleaning or processing when used in soldered assembly.



B. Mounting tab corner profile according to package version.





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